SCAS458D - DECEMBER 1994 - REVISED APRIL 1996

- Four CPU Clock Outputs With Programmable Frequency (50 MHz, 60 MHz, and 66 MHz)
- Six Clock Outputs at Half-CPU Frequency for PCI
- One 24-MHz Clock Output
- One 12-MHz Clock Output
- Two 14.318-MHz Reference Outputs
- All Output Clock Frequencies Derived From a Single 14.31818-MHz Crystal Input
- LVTTL-Compatible Inputs and Outputs
- Internal Loop Filters for Phase-Lock Loops Eliminate the Need for External Components
- Operates at 3.3 V<sub>CC</sub>
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- Packaged in Plastic Small-Outline Package

#### **DW PACKAGE** (TOP VIEW) $V_{CC}$ 28 REF0 27 REF1 X1 🛮 2 26 V<sub>CC</sub> X2 **□** 3 GND ¶4 25 CLK12 24 CLK24 OE Π 5 PCLK0 ¶ 6 23 | GND PCLK1 7 22 BCLK2 21 BCLK3 V<sub>CC</sub> **[**] 8 20 VCC PCLK2 ¶9 PCLK3 10 19 BCLK4 GND [] 11 18 BCLK5 SEL1 **∏** 12 17 | GND 16 BCLK1 SEL0 **1**3 V<sub>CC</sub>L 14 15 BCLK0

### description

The CDC9841 is a high-performance clock synthesizer/driver that generates all required clock signals necessary for a high-performance PC motherboard. The four central processing unit (CPU) clock outputs (PCLKn) are programmable to one of three frequencies (50 MHz, 60 MHz, or 66 MHz) via the SEL0 and SEL1 control inputs. The six peripheral-component-interconnect (PCI) clock outputs (BCLKn) are half the frequency of PCLKn and are delayed 1 ns to 4 ns from the rising edge of the CPU clock. In addition, the four fixed-frequency outputs provide a 24-MHz clock (CLK24), a 12-MHz clock (CLK12), and two buffered copies of the 14.318-MHz input reference (REF0, REF1).

The CDC9841 generates all output frequencies from a 14.31818-MHz crystal input. A reference clock can be provided at X1 instead of a crystal input.

Two phase-lock loops (PLLs) generate the CPU clock frequency and the 24-MHz clock frequency. On-chip loop filters and internal feedback eliminate the need for external components. The PCI and 12-MHz clock frequencies are derived from the base CPU and 24-MHz clock frequencies, respectively. The PLL circuit can be bypassed in the TEST mode (i.e., SEL0 = SEL1 = H) to distribute a test clock provided at the X1 input. Because the CDC9841 is based on PLL circuitry, it requires a stabilization time to achieve phase lock of the PLL. This stabilization time is required following power up and application of a fixed-frequency, fixed-phase signal at the X1 input, as well as following any changes to the SELn inputs.

PCLKn and BCLKn provide low-skew/low-jitter clock signals for reliable clock operation. All outputs are 3 state and are enabled via OE.



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# CDC9841 PC MOTHERBOARD CLOCK SYNTHESIZER/DRIVER WITH 3-STATE OUTPUTS SCAS458D - DECEMBER 1994 - REVISED APRIL 1996

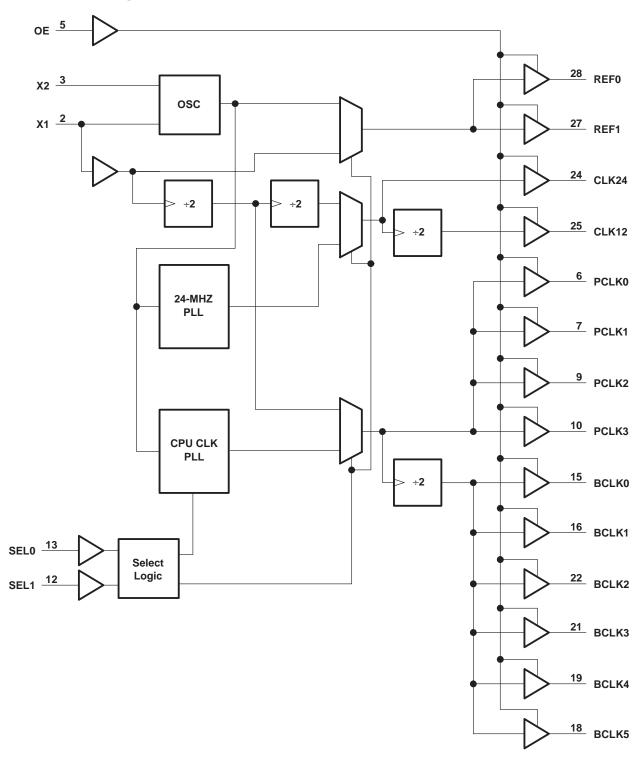
### **FUNCTION TABLE**

OE	SEL0	SEL1	X1	PCLKn	BCLKn	REFn	CLK24	CLK12
L	Х	Х	14.31818 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
Н	L	L	14.31818 MHz	50 MHz	25 MHz	14.318 MHz	24 MHz	12 MHz
Н	L	Н	14.31818 MHz	60 MHz	30 MHz	14.318 MHz	24 MHz	12 MHz
Н	Н	L	14.31818 MHz	66 MHz	33 MHz	14.318 MHz	24 MHz	12 MHz
Н	Н	Н	TCLK <sup>†</sup>	TCLK/2	TCLK/4	TCLK	TCLK/4	TCLK/8

<sup>†</sup> TCLK is a test clock input at the X1 input during test mode.



## functional block diagram



## CDC9841 PC MOTHERBOARD CLOCK SYNTHESIZER/DRIVER WITH 3-STATE OUTPUTS

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 4.6 V
Voltage range applied to any output in the high state or power-off state,	
V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, I <sub>O</sub>	2 × I <sub>OHmax</sub>
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT	
Vcc	Supply voltage				V	
VIH	High-level input voltage		2		V	
VIL	Low-level input voltage			0.8	V	
VI	Input voltage		0	Vcc	V	
		REF0		-12		
	High-level output current	REF1		-8	mA	
ЮН		PCLKn		-6		
		BCLKn		-12		
		CLK24, CLK12		-4		
		REF0		12		
	Low-level output current	REF1		8	mA	
loL		PCLKn		6		
		BCLKn		12		
	CLK24, CLK12					
TA	Operating free-air temperature	·	0	70	°C	

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				UNIT	
VIK	V <sub>CC</sub> = 3.135 V,	I <sub>I</sub> = -18 mA			-1.2	V	
		$I_{OH} = -12 \text{ mA}$	REF0	2.5			
		$I_{OH} = -8 \text{ mA}$	REF1	2.5		V	
VOH	V <sub>CC</sub> = 3.135 V	$I_{OH} = -6 \text{ mA}$	PCLKn	2.5			
		$I_{OH} = -12 \text{ mA}$	BCLKn	2.5			
		$I_{OH} = -4 \text{ mA}$	CLK24, CLK12	2.5			
		I <sub>OL</sub> = 12 mA	REF0		0.4		
		I <sub>OL</sub> = 8 mA	REF1		0.4		
V <sub>OL</sub>	V <sub>CC</sub> = 3.135 V	$I_{OL} = 6 \text{ mA}$	PCLKn		0.4	V	
		I <sub>OL</sub> = 12 mA	BCLKn		0.4		
		I <sub>OL</sub> = 4 mA	CLK24, CLK12		0.4		
lı	V <sub>CC</sub> = 3.6 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1	μΑ	
loz	V <sub>CC</sub> = 3.6 V,	$V_O = V_{CC}$ or GND			±10	μΑ	
laa	V <sub>CC</sub> = 3.6 V,	I <sub>O</sub> = 0,	Outputs enabled <sup>†</sup>		50	A	
lcc	$V_I = V_{CC}$ or GND		Outputs disabled		1	mA	
Ci	$V_I = V_{CC}$ or GND					pF	
Co	$V_O = V_{CC}$ or GND		_			pF	
C <sub>pd</sub>	V <sub>I</sub> = 3 V or 0					pF	

<sup>†</sup> Device in normal operating mode with no load on outputs

# timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
	After SEL1, SEL0		5	
Stabilization time‡	After OE↑		5	ms
	After power up		5	

<sup>&</sup>lt;sup>‡</sup> Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. In order for phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at X1. Until phase lock is obtained, the specifications for propagation delay and skew parameters given in the switching characteristics table are not applicable.



# CDC9841 PC MOTHERBOARD CLOCK SYNTHESIZER/DRIVER WITH 3-STATE OUTPUTS SCAS458D - DECEMBER 1994 - REVISED APRIL 1996

### switching characteristics (see Figures 1 and 2)

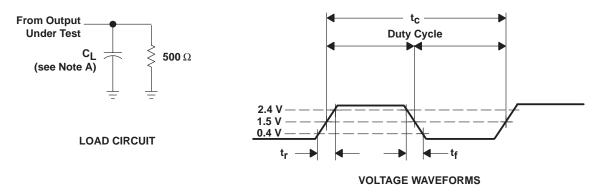
PARAMETER	FROM (INPUT)	TO (OUTPL	V <sub>CC</sub> = 3.135 V to 3.6 V, T <sub>A</sub> = 0°C to 70°C		UNIT	
			MIN	MAX		
. +		PCLKn (C <sub>L</sub> =	= 20 pF)		200	ps
t <sub>skew</sub> †		BCLKn (C <sub>L</sub> :	= 30 pF)		400	
Offset <sup>†</sup>	PCLKn (C <sub>L</sub> = 20 pF)	BCLKn (C <sub>L</sub> =	= 30 pF)	1	4	ns
Ť		PCLKn (C <sub>L</sub> = 20 pF)			±250	ps
Jitter <sup>T</sup>		BCLKn (C <sub>L</sub> =		±350		
Duty cycle†		Any output		45%	55%	
		PCLKn (C <sub>L</sub> = 20 pF)	SEL0 = L, SEL1 = L	20		
			SEL0 = L, SEL1 = H	16.7		
			SEL0 = H, SEL1 = L	15		ns
t <sub>C</sub>			SEL0 = L, SEL1 = L	40		113
		BCLKn ( $C_L = 30 pF$ )	SEL0 = L, SEL1 = H	33.3		
			SEL0 = H, SEL1 = L	30		
t <sub>r</sub> †‡		PCLKn (C <sub>L</sub> = 20 pF), BCLKn (C <sub>L</sub> = 30 pF)			2	ns
t <sub>f</sub> †‡		PCLKn (C <sub>L</sub> = 20 pF), B		2	ns	

<sup>†</sup> Specifications are applicable only after the PLL stabilization time has elapsed.



<sup>‡</sup> Rise and fall times are characterized using the load circuits shown in Figure 1.

# PARAMETER MEASUREMENT INFORMATION CLOCK DRIVER CIRCUITS



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

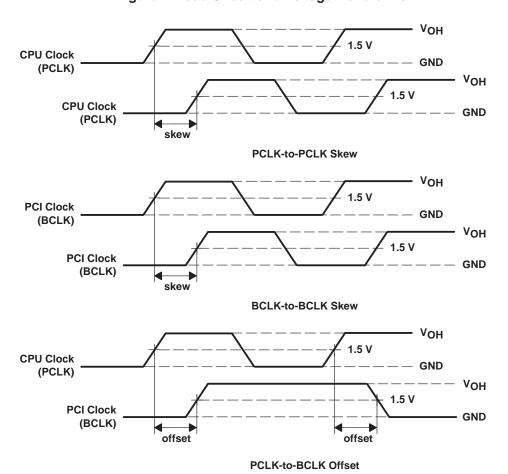


Figure 2. Waveforms for Calculation of t<sub>skew</sub> and Offset



### PACKAGE OPTION ADDENDUM

30-Mar-2005

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CDC9841DW	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI
CDC9841DWR	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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